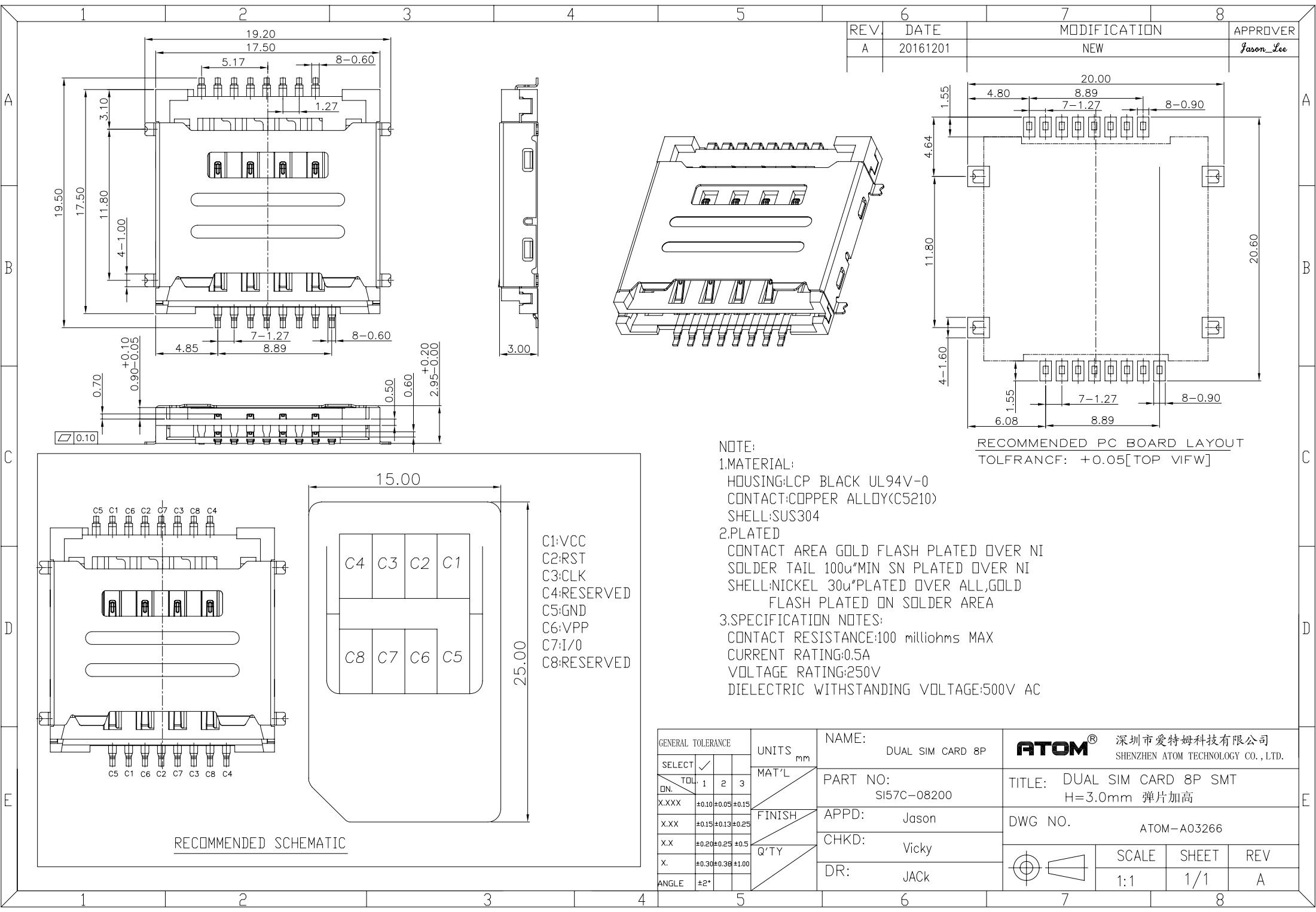


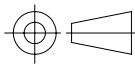


REV.	DATE	MODIFICATION	APPROVER
A	20161201	NEW	Jason_Lee

NOTE:
1.MATERIAL:
HOUSING:LCP BLACK UL94V-0
CONTACT: COPPER ALLOY(C5210)
SHELL:SUS304
2.PLATED
CONTACT AREA GOLD FLASH PLATED OVER NI
SOLDER TAIL 100u"MIN SN PLATED OVER NI
SHELL:NICKEL 30u"PLATED OVER ALL,GOLD
FLASH PLATED ON SOLDER AREA
3.SPECIFICATION NOTES:
CONTACT RESISTANCE:100 milliohms MAX
CURRENT RATING:0.5A
VOLTAGE RATING:250V
DIELECTRIC WITHSTANDING VOLTAGE:500V AC

RECOMMENDED PC BOARD LAYOUT
TOLFRANCE: +0.05[TOP VIFW]

C1:VCC
C2:RST
C3:CLK
C4:RESERVED
C5:GND
C6:VPP
C7:I/O
C8:RESERVED

GENERAL TOLERANCE				UNITS mm	NAME: DUAL SIM CARD 8P		ATOM [®] 深圳市爱特姆科技有限公司 SHENZHEN ATOM TECHNOLOGY CO., LTD.				
SELECT	✓				MAT'L	PART NO: SI57C-08200	TITLE: DUAL SIM CARD 8P SMT H=3.0mm 弹片加高				
DN.	TOL	1	2	3							
X.XXX		±0.10	±0.05	±0.15	FINISH	APPD: Jason	DWG NO. ATOM-A03266				
X.XX		±0.15	±0.13	±0.25							
X.X		±0.20	±0.25	±0.5	Q'TY	CHKD: Vicky					
X.		±0.30	±0.38	±1.00							
ANGLE		±2°			DR: JACK	SCALE: 1:1				SHEET: 1/1	REV: A